DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

SEND CORRESPONDENCE TO:

3475 Edison Way. Ste. L

Glenn Patent Grou

Menlo Park, CA 94025

.

My residence, post office address, and citizenship are as stated below next to my name;

I believe I am the original, first, and sole inventor (if only one name is listed below) or an original, first, and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

SEMICONDUCTOR LIGHT EMITTING DEVICE AND METHOD FOR MANUFACTURING THE SAME

		hich (check one) X is							/:•
applicable		on Serial No		and	was :	amended	on		(if
I hereby s including t	tate that I h he claims, a	nave reviewed and un as amended by any ar	derstand the c nendment refe	ontents rred to	of the	e above-id	entified	1 specificat	tion,
		ity to disclose informa tle 37, Code of Federa					on of t	his applica	ıtion
application	n(s) for pate n for patent	n priority benefits under ent or inventor's certificate or inventor's certificate	cate listed belo	w and I	nave a	lso identif	ed bel	ow any fore	eign
Prior Foreign Application(s)						Priority Claimed Yes No			
Number	Country	Day/Month/Year Fi	led				<u> </u>	_	
Number	Country	Day/Month/Year Fi	led					-	
Number	Country	Day/Month/Year Fi	led					-	
=====		=======================================		====	====	-====	====	:=====	
agent(s) to	OF ATTOR o prosecute therewith:	NEY: As a named in this application and	nventor, I here transact all bu	eby app Isiness	oint the	ne followir Patent a	ng atto nd Tra	rney(s) and demark Of	d/or ifice
Michael A Reg. No. 4	. GLENN, f l3,284; Chr	Reg. No. 30,176 ; Don ist pher PEIL, Reg. I	ald M. HENDR No. 45,005; and	RICKS, I d Julia	Reg. N THOM	lo. 40,355 I AS , Reg.	; Kirk No. 52	D. WONG , 2,283	

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I hereby claim the benefit under Title 35, United States code, Section 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:									
Application Ser. No. Filing Date Status: Patented, Pending, Abandoned									
I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.									
Full name of sole or first inventor: Tzong-Liang TSAI									
Inventor's signature Song June 19, 2003 Date									
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Full name of second joint inventor: Chih-Sung CHANG									
Inventor's signature Chih-Sung Chang June 19, 2003									
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